

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "UA7808CKCSE3"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
UA7808CKCSE3	SN	Level-NC-NC-NC	Ext-Mfg	KCS 3	10.15x15.4x4.5	2412.9

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.178217	99.997195	999972	0.007386	74
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000561	6	0	0
Precious Metals	Silver	7440-22-4	0.000004	0.002244	22	0	0
Sub-Total			0.178222	100	1000000	0.007386	74
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.735668	87.000041	870000	0.030489	305
Thermoplastics	Epoxy	85954-11-6	0.109927	12.999959	130000	0.004556	46
Sub-Total			0.845595	100	1000000	0.035045	350
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	1370.0144	99.565	995650	56.779025	567790
Copper and Its Alloys	Iron	7439-89-6	1.376	0.1	1000	0.057027	570
Copper and Its Alloys	Phosphorus	7723-14-0	4.472	0.325	3250	0.185338	1853
Precious Metals	Silver	7440-22-4	0.1376	0.01	100	0.005703	57
Sub-Total			1376	100	1000000	57.027093	570271
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	26.15	100	1000000	1.083763	10838
Sub-Total			26.15	100	1000000	1.083763	10838
Mold Compound							
Other inorganic Materials	Silica	7631-86-9	777.61355	77.2	772000	32.2275	322275
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	75.545358	7.5	75000	3.13091	31309
Other Plastics and Rubber	Carbon Black	1333-86-4	3.021814	0.3	3000	0.125236	1252
Thermoplastics	Epoxy	85954-11-6	151.090716	15	150000	6.26182	62618
Sub-Total			1007.271438	100	1000000	41.745466	417455
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.442961	100	1000000	0.101246	1012
Sub-Total			2.442961	100	1000000	0.101246	1012
Total			2412.888216			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.